

## DAFTAR PUSTAKA

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**Lampiran 1.** Daftar Pertanyaan Penilaian Studi untuk *Systematic Review* menggunakan Modifikasi *Ex Vivo And In Vivo Modified RoB Tools*

KOMPONEN	KOMENTAR / KLARIFIKASI
1. Apakah asesor / analis data blinded ?	<b>Ya</b> : <i>Blinding</i> dilakukan dan dijelaskan secara memadai. <b>Tidak</b> : <i>Blinding</i> tidak disebutkan dan/atau eksperimen selalu dilakukan dalam urutan yang sama atau prosesnya tidak cukup dijelaskan
2. Apakah sampel diperiksa stabilitas dan kualitasnya?	<b>Ya</b> : Studi ini termasuk pemeriksaan sampel gigi dan jenis resin komposit yang digunakan (jika ada). <b>Tidak</b> : Pemeriksaan tidak dijelaskan, atau pemeriksaan dilakukan, tetapi tidak ditentukan konsekuensinya.
3. Apakah penulis memverifikasi intervensinya ?	<b>Ya</b> : <i>Bond strength</i> pada email atau dentin <b>Tidak</b> : Tidak ada yang diukur atau dilaporkan
4. Apakah penulis memverifikasi tahapan/ langkah sistem adhesif yang digunakan?	<b>Ya</b> : Disebutkan kedua tahapan/langkah sistem adhesif yang digunakan <b>Tidak</b> : Satu tahapan/langkah sistem adhesif tidak dilaporkan <b>Tidak jelas</b> : Mode tahapan/langkah sistem adhesif dilaporkan, tetapi tidak jelas apakah nilai tersebut diukur atau bagaimana
5. Apakah tidak ada pelaporan hasil yang selektif?	<b>Ya</b> : Tidak, ada indikasi untuk pelaporan hasil selektif <b>Tidak</b> : Efek dijelaskan, tetapi tidak ada data yang ditampilkan

6. Apakah jenis gigi yang digunakan dijelaskan dengan benar?	<b>Ya</b> : Penulis menyebutkan jenis gigi dan kriterianya <b>Tidak</b> : Penulis tidak menjelaskan satu atau lebih karakteristik di atas
7. Apakah permukaan email atau dentin dari spesimen gigi dikasarkan ?	<b>Ya</b> : Penulis menjelaskan karakteristik di atas <b>Tidak</b> : Penulis tidak menjelaskan karakteristik di atas
8. Apakah ukuran kelompok didasarkan pada analisis <i>bond strength</i> ?	<b>Ya</b> : Analisis <i>bond strength</i> yang tepat telah dijelaskan <b>Tidak</b> : Analisis <i>bond strength</i> tidak dijelaskan atau disebutkan
9. Apakah penelitian dipublikasikan dalam jurnal peer review?	<b>Ya</b> <b>Tidak</b>
10. Apakah studi telah disetujui oleh Komite Etik ?	<b>Ya</b> <b>Tidak</b>
11. Apakah tidak ada pernyataan konflik kepentingan?	<b>Ya</b> <b>Tidak</b> <b>Tidak Jelas</b> : Tidak disebutkan

**Lampiran 2.** Daftar Produk Sistem Adhesif Yang Digunakan Dan Komposisinya

PRODUK	JENIS SISTEM ADHESIF	KOMPOSISI
Adper Scotchbond Multi-Purpose 3M ESPE	3-Step Etch-And-Rinse Systems	<b>Etchant</b> : 35% phosphoric acid <b>Primer</b> : HEMA, polyalkenoic acid copolymer, water <b>Adhesive</b> : bis-GMA, HEMA, photoinitiator
All-Bond 2 BISCO	3-Step Etch-And-Rinse Systems	<b>Primer A</b> : NTG-GMA, acetone, ethanol, water <b>Primer B</b> : BPDM, acetone, ethanol, photoinitiator <b>Adhesive</b> : bis-GMA, HEMA, camphorquinone, amine activator. <b>Etchant</b> : 32% phosphoric acid with benzalkonium chloride
OptiBond FL KERR	3-Step Etch-And-Rinse Systems	<b>Primer</b> : HEMA, GPDM, PAMM, ethyl alcohol, camphorquinone, water <b>Adhesive</b> : bis-GMA, HEMA, barium aluminum borosilicate glass, fumed silica, disodiumhexafluorosilicate, glycerol dimethacrylate, camphorquinone <b>Etchant</b> : 37.5% phosphoric acid
Permaquick Ultradent	3-Step Etch-And-Rinse Systems	<b>Etchant</b> : 35% phosphoric acid <b>Primer</b> : Canadian balsam, HEMA, methacrylic acid, camphorquinone, phosphate monomer in ethanol <b>Adhesive</b> : bis-GMA, TEGDMA, HEMA, diluent monomer, tertiary amine, camphorquinone, proprietary glass silicate filler
One-Step Bisco	2-Step Etch-And-Rinse Systems	<b>Etchant</b> : 32% phosphoric acid with benzalkonium chloride. <b>Adhesive</b> : bis-GMA, HEMA, BPDM, acetone, photoinitiator
Prime & Bond NT Dual Cure Dentsply	2-Step Etch-And-Rinse Systems	<b>Etchant</b> : 34% phosphoric acid, water, silicon dioxide, surfactants, blue colorant <b>Adhesive</b> : dimethacrylate resin , trimethacrylate resins,

		dipentaerythritol penta acrylate monophosphate, nanofillers, amorphous silicon dioxide, photoinitiators, stabilizers, cetylamine hydrofluoride, acetone
Single Bond Plus 3 M ESPE	2-Step Etch-And-Rinse System	Bis-GMA, HEMA, DMA, ethanol, water, photoinitiator, methacrylate functional copolymer of polyacrylic and polyitaconic acids, silica fillers. <b>Etchant :</b> 35% phosphoric acid.
Syntac Ivoclar Vivadent	2-Step Etch-And-Rinse Systems	<b>Primer</b> : polyethylene glycol dimethacrylate, maleic acid, ketone <b>Adhesive</b> : polyethylene glycol dimethacrylate, glutaraldehyde Heliobond : bis-GMA, triethylene glycoldimethacrylate, photoinitiator
Adper Single Bond 2 3m ESPE	2-Step Etch-And-Rinse Systems	<b>Etchant</b> : 35% phosphoric acid (Scotchbond Etchant) <b>Adhesive</b> : bis-GMA, HEMA, dimethacrylates, ethanol, water, photoinitiator, methacrylate functional copolymer of polyacrylic and poly(itaconic) acids, 10% by weight of 5 nm-diameter spherical silica particles
Solobond M VOCO	2-Step Etch And Rinse System	Bis-GMA, HEMA, BHT, acetone, organic acids.
Prime&Bond One	2-Step Etch And Rinse System	PENTA, TCB resin, UDMA, TEGDMA, HEMA, Nanofillers, Camphorquinone, BMBE, Butylated benzenediol, T butanol solvent
Clearfil SE Bond Kuraray	2-Step Self-Etch System	<b>Primer</b> : 10-MDP, HEMA, DMA, photoinitiator, water. <b>Bond</b> : 10-MDP, HEMA, bis-GMA, DMA, microfiller, photoinitiator.
Clearfil SE Protect Kuraray	2-Step Self Etch Adhesive System	<b>Primer</b> : 10-MDP, 12-MDPB, HEMA, hydrophilic dimethacrylate, water. <b>Bond</b> : 10 MDP, Bis-GMA, HEMA, hydrophobic dimethacrylate, dicamphorquinone, N,N-diethanol-p-toluidine silinated colloidal silica, surface-treated sodium fluoride.
Adper Prompt	1-Step Self-Etch	<b>Solution-A</b> : bis-GMA, methacrylated

3M ESPE	System	phosphoric esters, initiators based on camphorquinone, stabilizers. <b>Solution-B</b> : water, HEMA, polyalkenoic acid, stabilizers.
Adper Prompt L-Pop 3M ESPE	1-Step Self-Etch Systems	<b>Compartment #1</b> : methacrylate phosphates, photoinitiator, stabilizer <b>Compartment #2</b> : water, complexed fluorides, stabilizer
Futurabond NR VOCO	1-Step Self-Etch Systems	<b>Adhesive</b> : bis-GMA, hydroxyethylmethacrylate, BHT, ethanol, organic acids, fluoride, initiator
iBond Heraus KUzler	1-Step Self-Etch Systems	<b>Adhesive</b> : acetone, 4-META, glutaraldehyde, initiator
Xeno III Dentsply	1-Step Self-Etch Systems	<b>Liquid A</b> : HEMA, purified water, ethanol, BHT, highly dispersed silicon dioxide <b>Liquid B</b> : phosphoric acid modified polymethacrylate resin, mono fluorophosphazene modified methacrylate resin, UDMA
All Bond SE BISCO	1-Step Self Ecth Adhesive	<b>Part I</b> : Ethanol, sodium benzene sulfinate. <b>Part II</b> : HEMA, bis (glyceryl 1,3 dimethacrylate) phosphates, biphenyl dimetacrylate.
Peak Universal Adhesive System Ultradent	Universal Adhesive System	<b>Peak SE Primer</b> : ethyl alcohol, methacrylic acid, 2-hydroxyethyl methacrylate <b>Peak LC Bond resin</b> : ethyl alcohol, 2-hydroxyethyl methacrylate <b>Etchant</b> : 35% phosphoric acid
Scotchbond Universal Adhesive 3M ESPE	Universal Adhesive System	<b>Adhesive</b> : MDP phosphate monomer, dimethacrylate resins, HEMA, methacrylate-modified polyalkenoic acid copolymer, filler, ethanol, water, initiators, silane <b>Etchant</b> : 34% phosphoric acid, water, synthetic amorphous silica, polyethylene glycol, aluminium oxide. (Scotchbond Universal Etchant)
All-Bond Universal	Universal Adhesive	<b>Adhesive</b> : MDP, bis-GMA, HEMA, ethanol, water, initiators

BISCO	System	<b>Etchant Uni-Etch</b> : 32% phosphoric acid, benzalkonium Chloride
Filtek Silorane Adhesive	Silorane Adhesive System	Hydrophobic dimethacrylate, phosphorylated methacrylates, TEGDMA, silorane-treated silica filler.
Filtek Silorane Primer		Phosphorylated methacrylates, vitrebond copolymer, Bis-GMA, HEMA, water, ethanol, silorane-treated silica filler.
3M ESPE		















